

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Rajiv K. Mongia</td> <td>12/20/2005</td> </tr> <tr> <td>Himanshu Pokharna</td> <td>12/24/2005</td> </tr> <tr> <td>Eric DiStefano</td> <td>12/20/2005</td> </tr> </tbody> </table>		Name	Execution Date	Rajiv K. Mongia	12/20/2005	Himanshu Pokharna	12/24/2005	Eric DiStefano	12/20/2005
Name	Execution Date								
Rajiv K. Mongia	12/20/2005								
Himanshu Pokharna	12/24/2005								
Eric DiStefano	12/20/2005								
RECEIVING PARTY DATA									
Name:	Intel Corporation								
Street Address:	2200 Mission College Blvd.								
City:	Santa Clara								
State/Country:	CALIFORNIA								
Postal Code:	95052								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11239957</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11239957				
Property Type	Number								
Application Number:	11239957								
CORRESPONDENCE DATA									
Fax Number:	(203)972-7627								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	(203) 972-0006								
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Correspondent Name:	Buckley, Maschoff & Talwalkar LLC								
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ATTORNEY DOCKET NUMBER:	P21672/I06.412								
NAME OF SUBMITTER:	Nathaniel Levin								
Total Attachments: 3 source=P21672 - Signed Assignment for Mongia_Pokharna_DiStefano#page1.tif source=P21672 - Signed Assignment for Mongia_Pokharna_DiStefano#page2.tif									

OP \$40.00 11239957

ASSIGNMENT OF RIGHTS, TITLE AND INTEREST IN INVENTION

This is an Assignment of the following rights, title and interest: *(check all that apply)*

United States of America rights, title and interest in the invention

Foreign rights, title and interest in the invention

United States Patent Application Serial No.: 11/239,957

Date of Execution: Date of Filing: September 30, 2005

United States Provisional Patent Application No.:

United States Patent No(s).:

International (PCT) Patent Application Serial No.:

Other *(specify)*::

TITLE OF THE INVENTION:

IC COOLANT MICROCHANNEL ASSEMBLY WITH INTEGRATED ATTACHMENT HARDWARE

Inventors (assignors)

Name	Address
Rajiv K. Mongia	3532 Langdon Common, Fremont, CA 94538
Himanshu Pokharna	439 Camille Circle #13, San Jose, CA 95134
Eric DiStefano	1535 Frankfurt Way, Livermore, CA 94550

Assignee

Name	Address
Intel Corporation	2200 Mission College Blvd., Santa Clara, CA 95052 US

Whereas, we, the above-identified Inventors, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention");

And, whereas we desire to assign our above-identified rights, title and interest in the Invention to **Intel Corporation**, 2200 Mission College Blvd., Santa Clara, CA 95052 US;

Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged;


We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted or have granted for said Invention, and in and to any and all reissues and reexaminations thereof, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

And we further agree to sign and execute all necessary and lawful future documents, including applications for foreign patents, for filing divisions, continuations and continuations-in-part of said application for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for our aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.

Inventors' Signatures

20-Dec-2005
Date




Rajiv K. Mongia

~~20-Dec-2005~~
Date

Himanshu Pokharna

20-Dec-2005
Date



Eric DiStefano

Attorney Docket No.: P21672
(BMT Ref. No.: 105412)

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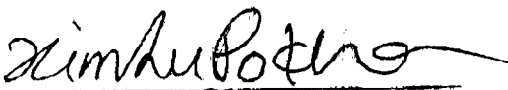
Inventor's Signatures

Date

Rajiv K. Mongia

24th Dec 2005

Date


Himanshu Pokharna

Date

Eric DiStefano